
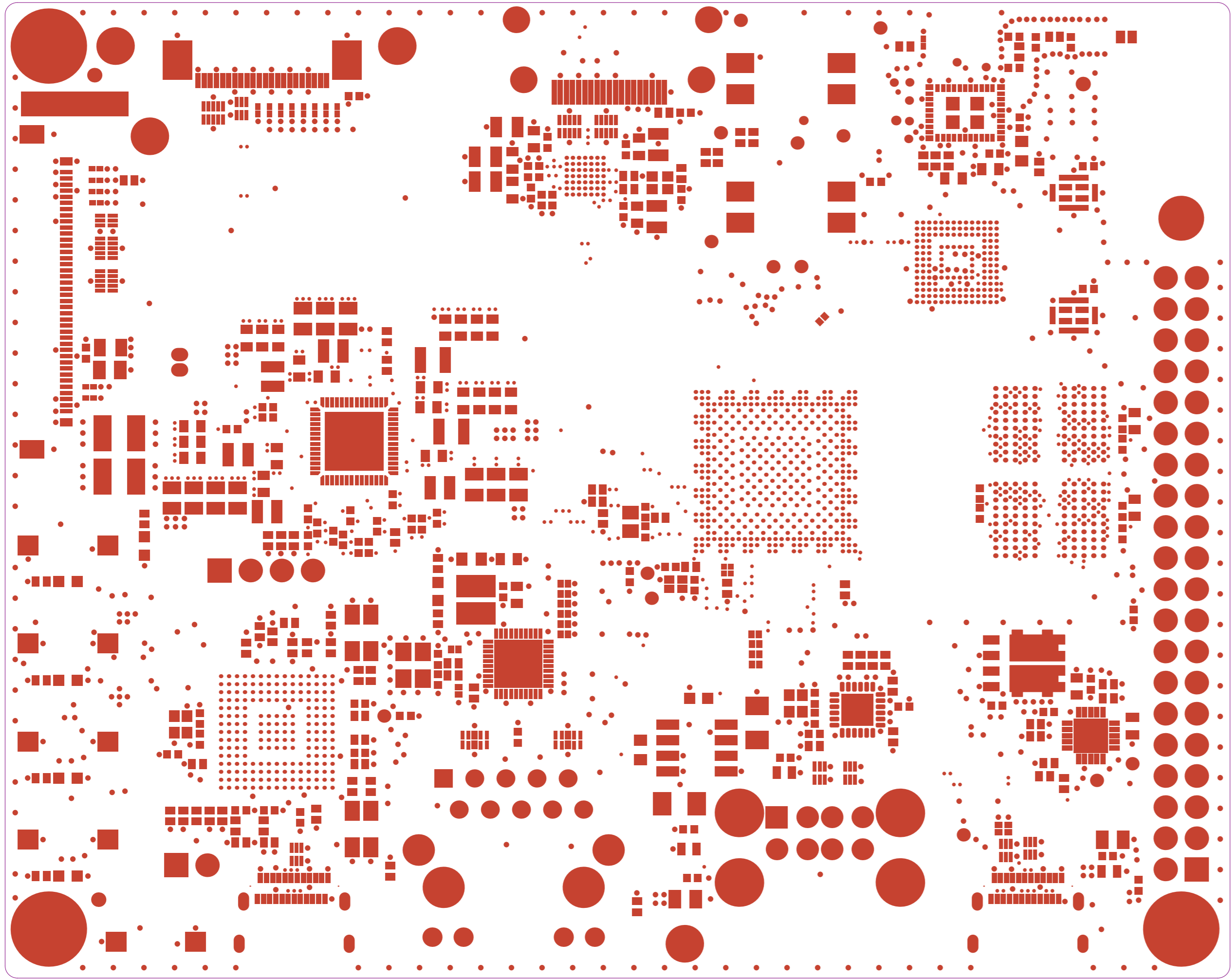

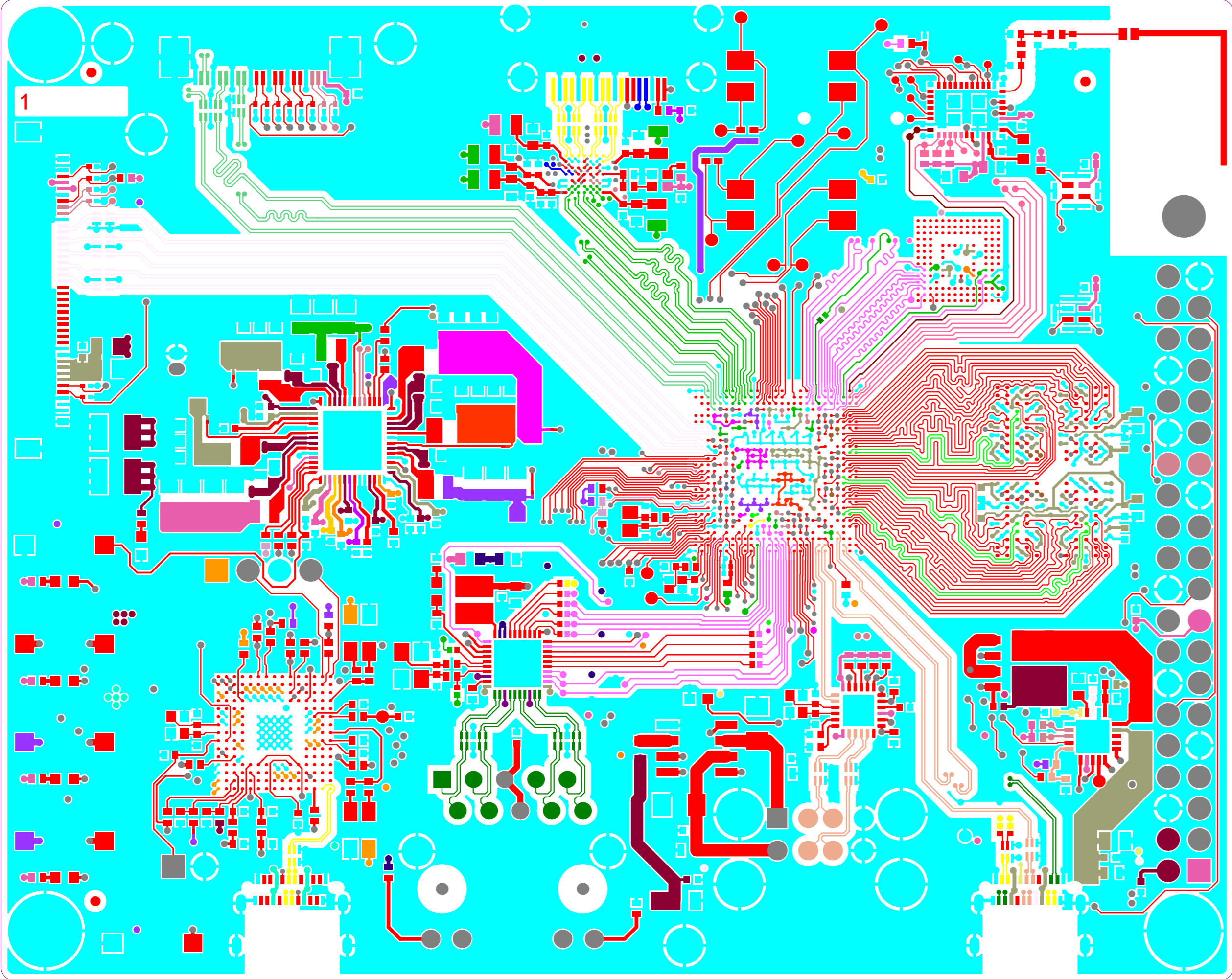


Project: STM32MP257-DK		
Layer: Top Overlay	Gerber: .GTO	
Variant: [No Variations]	Ref: MB1605	
Date: 03-JUN-24	Rev: C	



Project: STM32MP257-DK		
Layer: Top Solder	Gerber: .GTS	
Variant: [No Variations]	Ref: MB1605	
Date: 03-JUN-24	Rev: C	



Project: STM32MP257-DK

Layer: **Top Layer**

Variant: [No Variations]

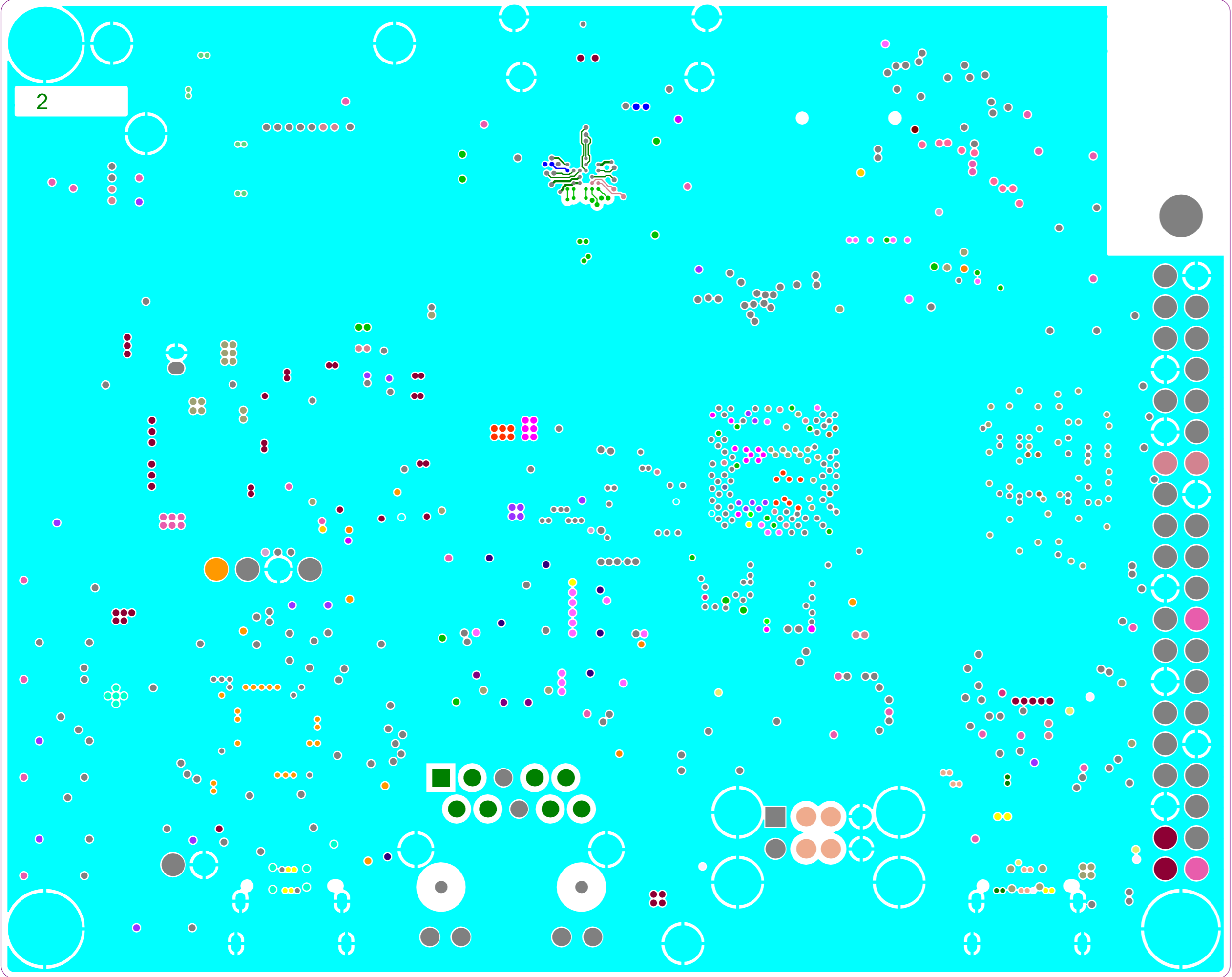
Date: 03-JUN-24


Gerber: **.GTL**

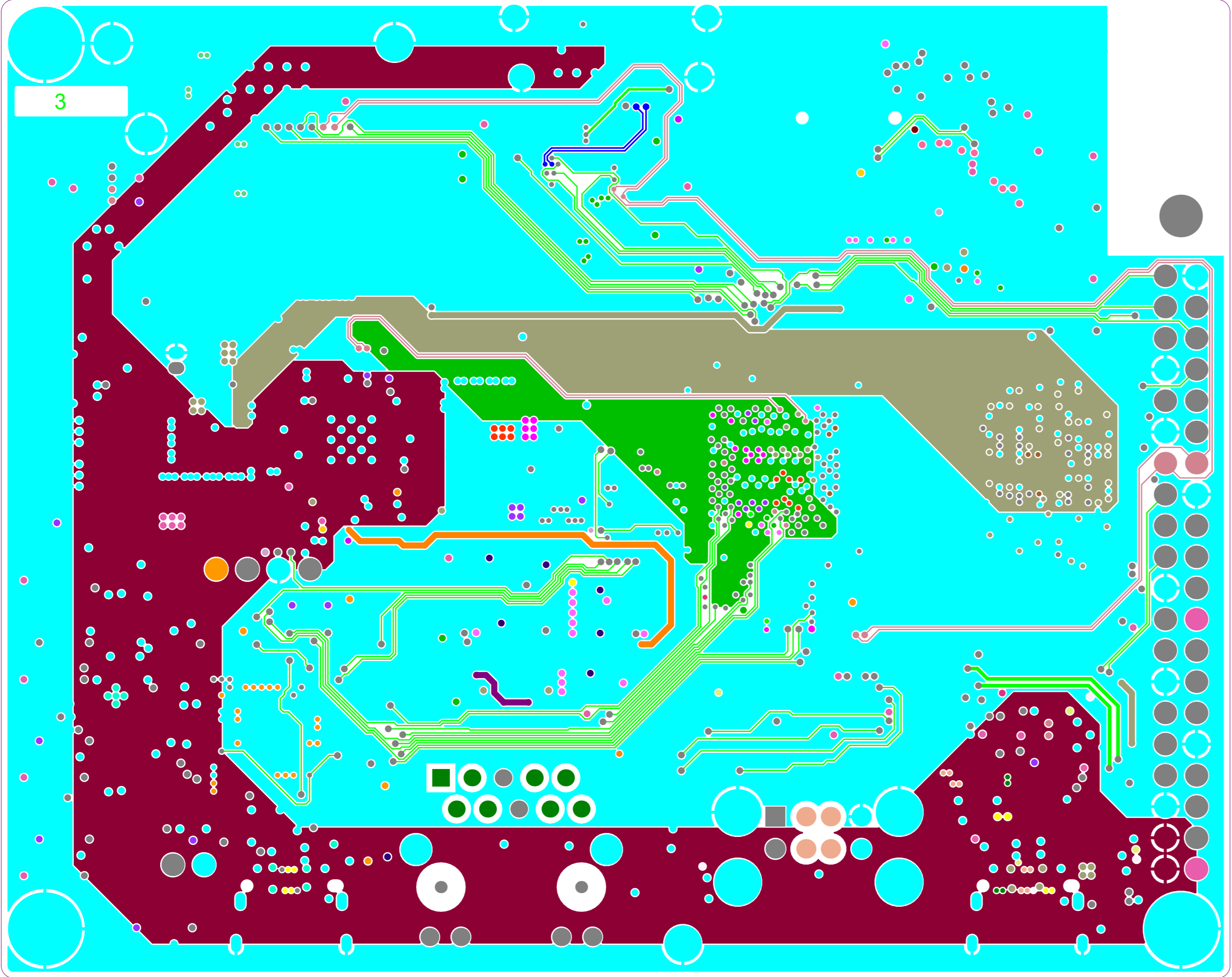
Ref: MB1605


Rev: C

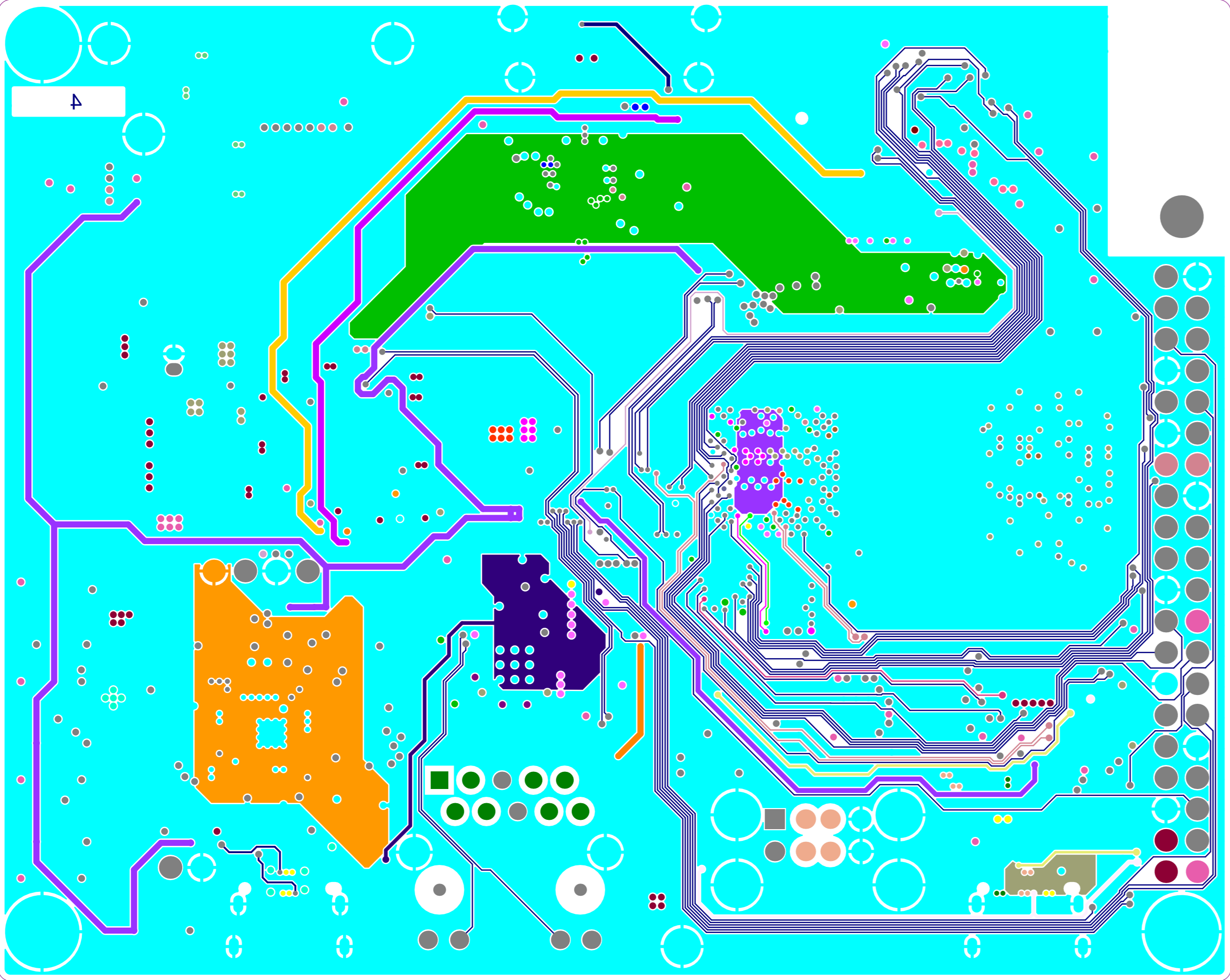





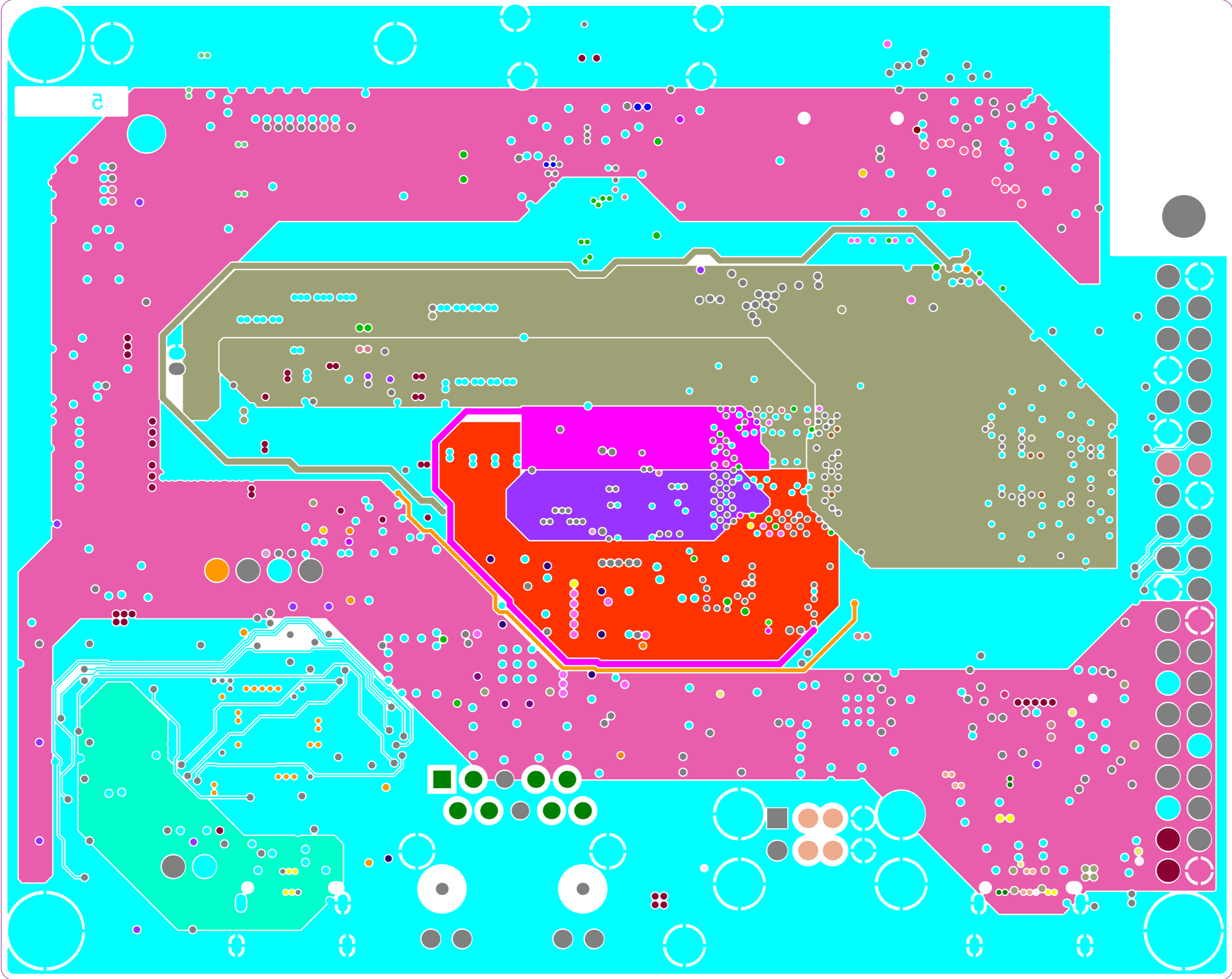
Project: STM32MP257-DK		
Layer: Signal Layer 1	Gerber: .G1	
Variant: [No Variations]	Ref: MB1605	
Date: 03-JUN-24	Rev: C	




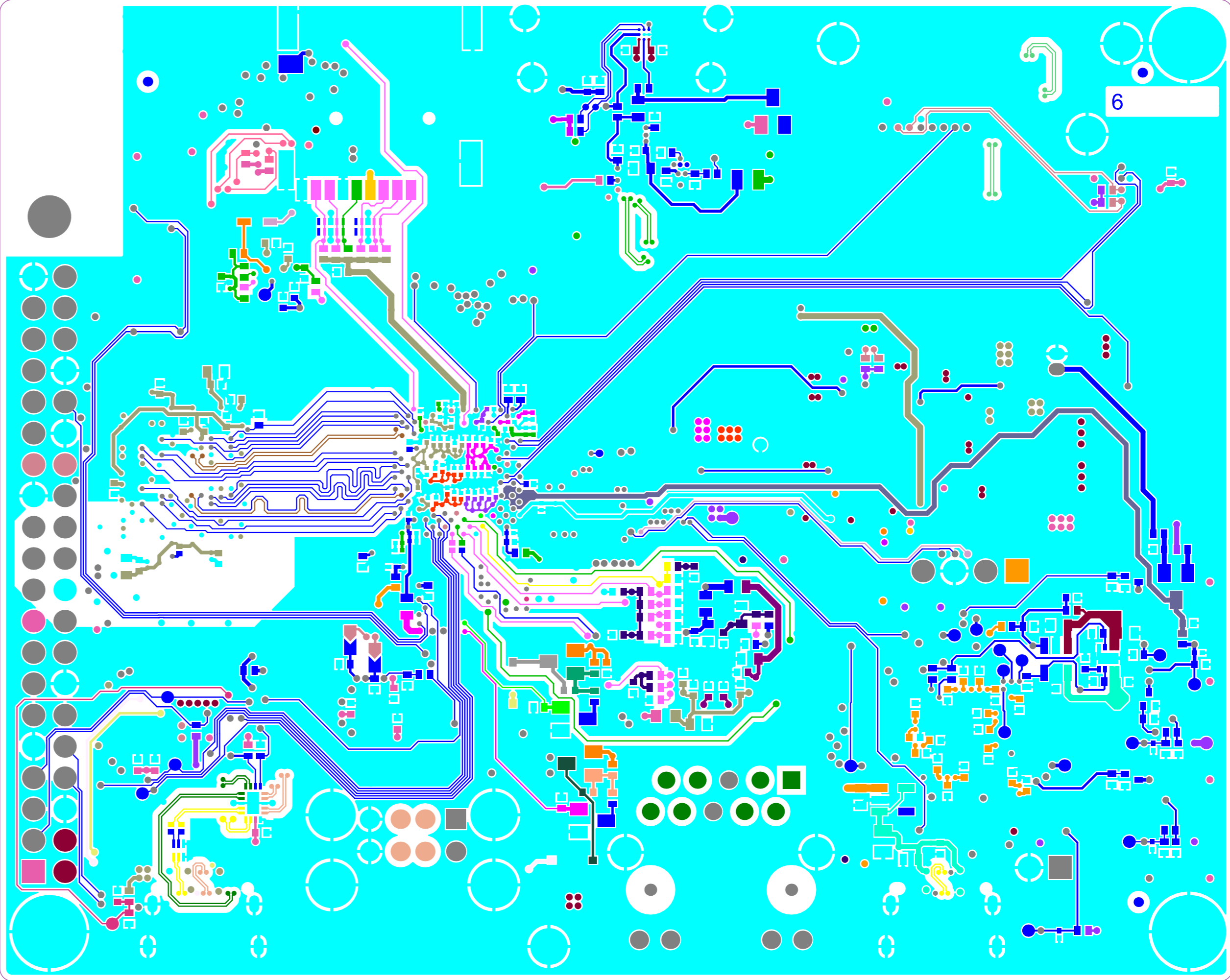
Project: STM32MP257-DK		
Layer: Signal Layer 2	Gerber: .G2	
Variant: [No Variations]	Ref: MB1605	
Date: 03-JUN-24	Rev: C	



Project: STM32MP257-DK		
Layer: Signal Layer 3	Gerber: .G3	
Variant: [No Variations]	Ref: MB1605	
Date: 03-JUN-24	Rev: C	



Project: STM32MP257-DK		
Layer: Signal Layer 4	Gerber: .G4	
Variant: [No Variations]	Ref: MB1605	
Date: 03-JUN-24	Rev: C	



Project: STM32MP257-DK

Layer: Bottom Layer

Variant: [No Variations]

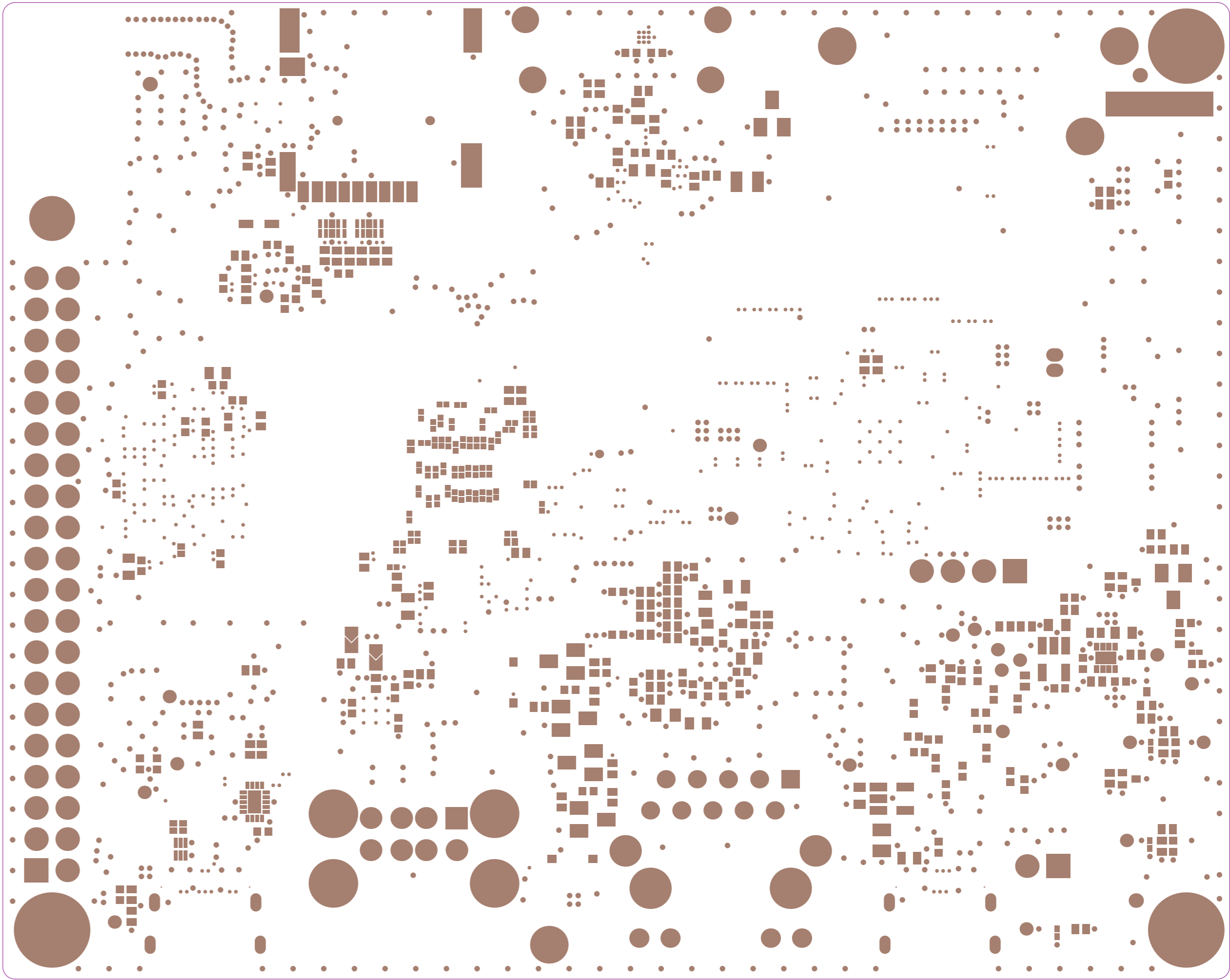
Date: 03-JUN-24

Gerber:.GBL

Ref: MB1605

Rev: C





Project: STM32MP257-DK

Layer: Bottom Solder

Variant: [No Variations]

Date: 03-JUN-24

Gerber:.GBS

Ref: MB1605

Rev: C





PCB SPECIFICATIONS :

A. MATERIAL :

FR-4

☐ TG-170

☒ TG-150

☐ TG-140

B. MATERIAL FAMILY :

N/A

C. SOLDERMASK COLOR :

☐ GREEN

☒ BLUE

☐ RED

☐ BLACK

D. SILKSCREEN COLOR :

☒ WHITE

☐ YELLOW

☐ BLACK

E. SURFACE FINISH :

☒ ENIG

☐ IMMERSION SILVER

☐ IMMERSION TIN

☐ HASL

☐ HASL (PB-FREE)

☐ GOLDEN FINGER

☐ IMPEDANCE CONTROL :

☐ NO

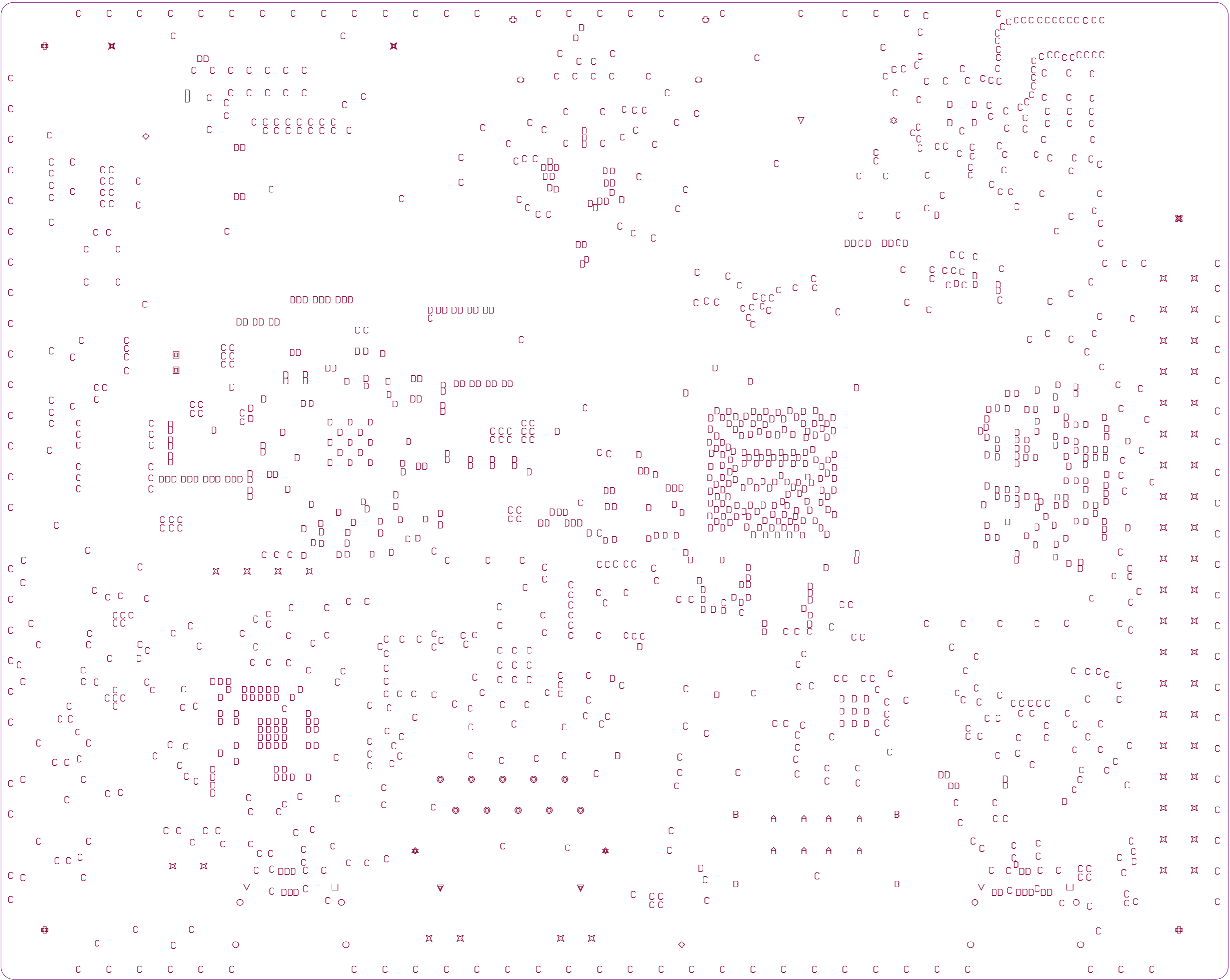
☒ YES


G. THROUGH VIA :

PLUG THE VIAS WHICH ARE COVERED WITH SOLDERMASK ONE OR TWO SIDE.
PLUG MATERIAL : ☒ SOLDERMASK ☐ NON-CONDUCTIVE EPOXY.

☐ STACK-UP :

SEE LAYER STACK-UP SEQUENCE FOR OVERALL THICKNESS.



Project: STM32MP257-DK		
Layer: Drill Drawing	Gerber: .DRL	
Variant: [No Variations]	Ref: MB1605	
Date: 03-JUN-24	Rev: C	

Layer	Name	Material	Thickness	Constant
	Top Overlay			
	Top Solder	Solder Resist	0,025mm	3.5
1	Top Layer		0,037mm	
	Dielectric 1		0,072mm	3.8
2	Signal Layer 1		0,035mm	
	Dielectric 2		0,500mm	5
3	Signal Layer 2		0,035mm	
	Dielectric 3		0,191mm	4.3
4	Signal Layer 3		0,035mm	
	Dielectric 4		0,500mm	5
5	Signal Layer 4		0,035mm	
	Dielectric 5		0,072mm	3.8
6	Bottom Layer		0,037mm	
	Bottom Solder	Solder Resist	0,025mm	3.5
	Bottom Overlay			

PCB : TYPE 4

ASPECT-RATIO, AXE Z :
6 :1 to 8 :1
LEVEL "B"

MINIMUN PARAMETERS

DEFAULT
TRACKS : 0.100mm
GAPS : 0.100mm

BGA :
TRACKS : 0.090mm
GAPS : 0.090mm

Symbol	Count	Hole Size	Plated	Hole Type	Drill Layer Pair	Via/Pad	Pad Shape	Hole Length
E	29	0.100mm	PTH	Round	Top Layer - Signal Layer 1	Via	Rounded	-
D	610	0.200mm	PTH	Round	Top Layer - Bottom Layer	Via	Rounded	-
C	823	0.350mm	PTH	Round	Top Layer - Bottom Layer	Via	Rounded	-
□	2	0.500mm	PTH	Round	Top Layer - Bottom Layer	Pad	Rounded	-
○	8	0.500mm	PTH	Slot	Top Layer - Bottom Layer	Pad	Rounded	1.100mm
▽	3	0.650mm	NPTH	Round	Top Layer - Bottom Layer	Pad	Rounded	-
□	2	0.650mm	NPTH	Slot	Top Layer - Bottom Layer	Pad	Rounded	0.950mm
✱	1	0.700mm	NPTH	Round	Top Layer - Bottom Layer	Pad	Rounded	-
◎	10	0.900mm	PTH	Round	Top Layer - Bottom Layer	Pad	(Mixed)	-
A	8	0.920mm	PTH	Round	Top Layer - Bottom Layer	Pad	(Mixed)	-
✱	50	1.000mm	PTH	Round	Top Layer - Bottom Layer	Pad	Rounded	-
◇	2	1.100mm	PTH	Round	Top Layer - Bottom Layer	Pad	Rounded	-
⊕	4	1.350mm	PTH	Round	Top Layer - Bottom Layer	Pad	Rounded	-
✱	2	1.700mm	PTH	Round	Top Layer - Bottom Layer	Pad	Rounded	-
✱	2	2.200mm	PTH	Round	Top Layer - Bottom Layer	Pad	Rounded	-
B	4	2.330mm	PTH	Round	Top Layer - Bottom Layer	Pad	Rounded	-
▽	2	3.200mm	NPTH	Round	Top Layer - Bottom Layer	Pad	Rounded	-
✱	1	3.500mm	NPTH	Round	Top Layer - Bottom Layer	Pad	Rounded	-
⊕	3	3.500mm	PTH	Round	Top Layer - Bottom Layer	Pad	Rounded	-
	1566 Total							

Slot definitions : Routed Path Length = Calculated from tool start centre position to tool end centre position.
Hole Length = Routed Path Length + Tool Size = Slot length as defined in the PCB layout